

SOT1840-6

FBGA621, fine-pitch ball grid array package; 621 terminals,
0.65 mm pitch, 17 mm x 17 mm x 1.97 mm body

10 July 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA621
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	28-05-2019
Manufacturer package code	98ASA01452D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	1.97	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	621	-	



FBGA621, fine-pitch ball grid array package; 621 terminals, 0.65 mm pitch, 17 mm x 17 mm x 1.97 mm body

2 Package outline

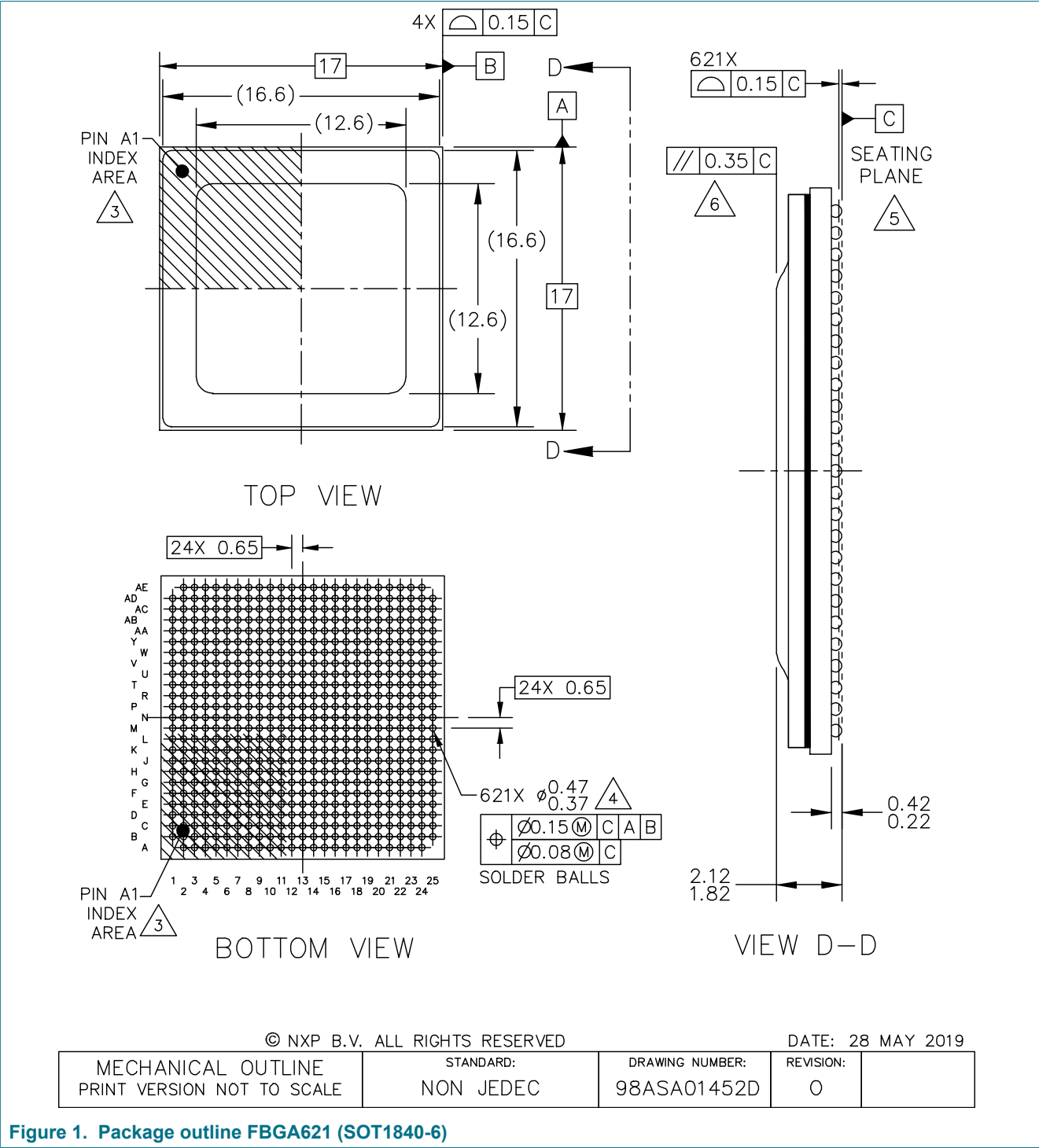


Figure 1. Package outline FBGA621 (SOT1840-6)

FBGA621, fine-pitch ball grid array package; 621 terminals, 0.65 mm pitch, 17 mm x 17 mm x 1.97 mm body

3 Soldering

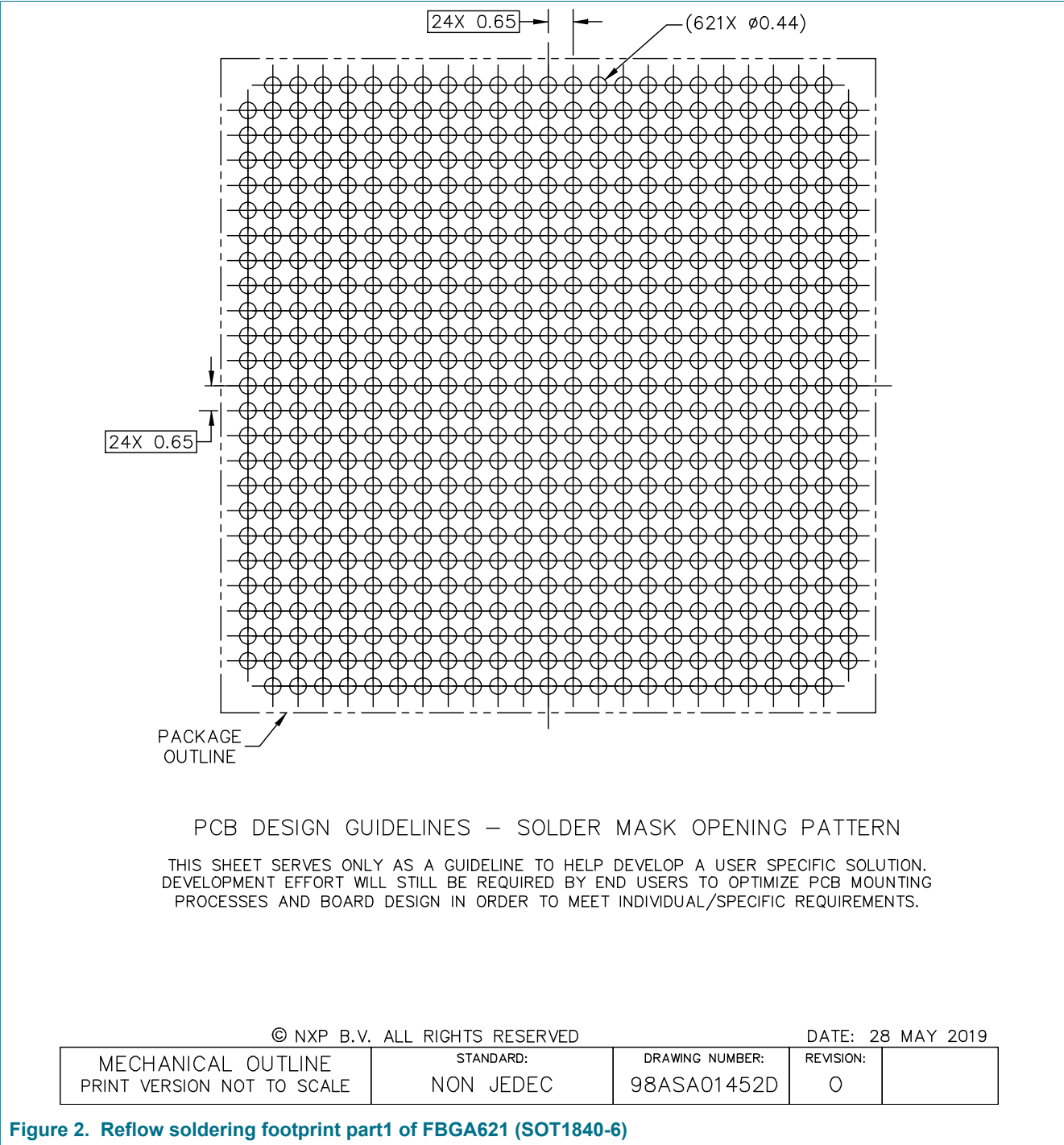


Figure 2. Reflow soldering footprint part1 of FBGA621 (SOT1840-6)

FBGA621, fine-pitch ball grid array package; 621 terminals, 0.65 mm pitch, 17 mm x 17 mm x 1.97 mm body

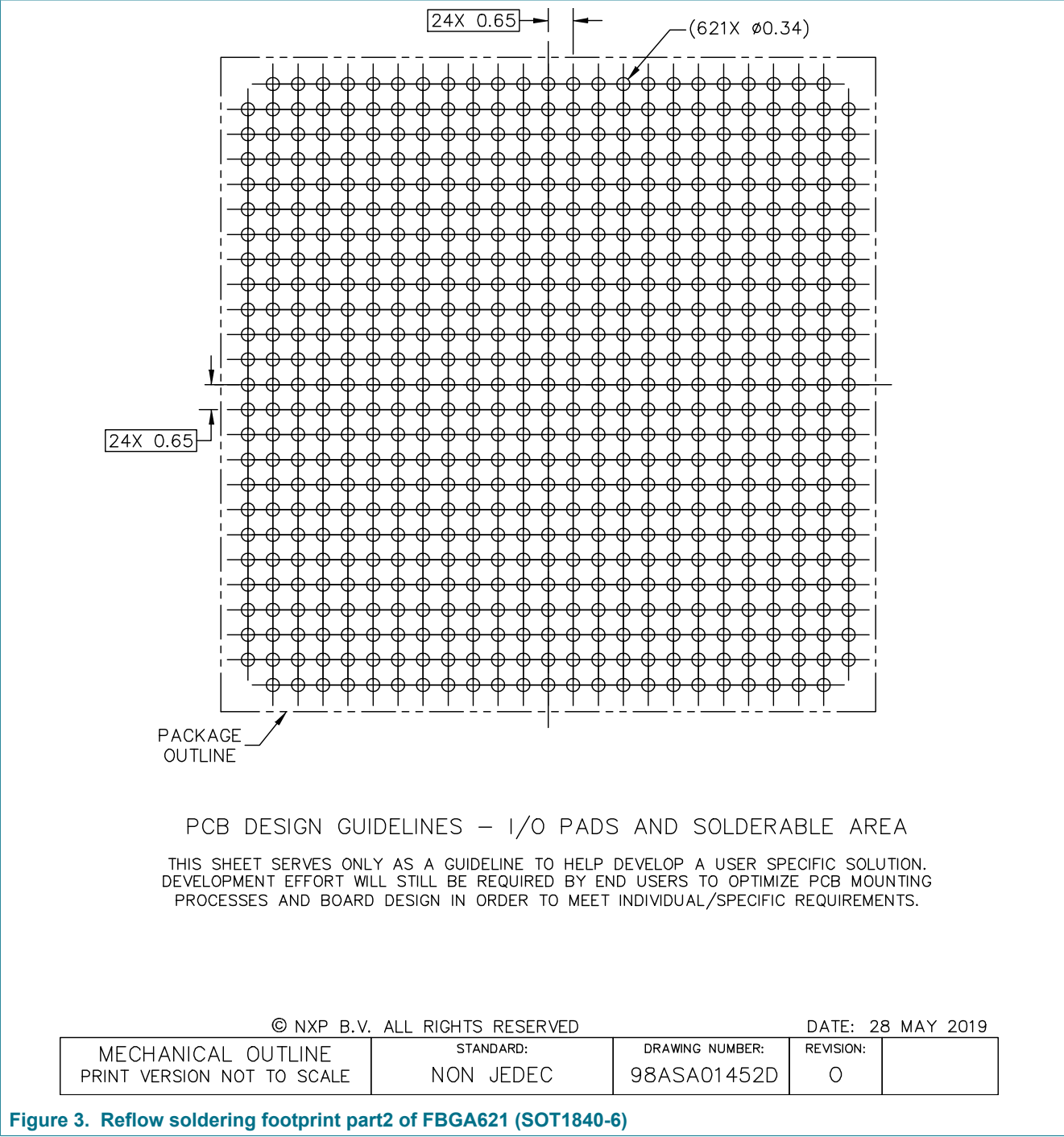
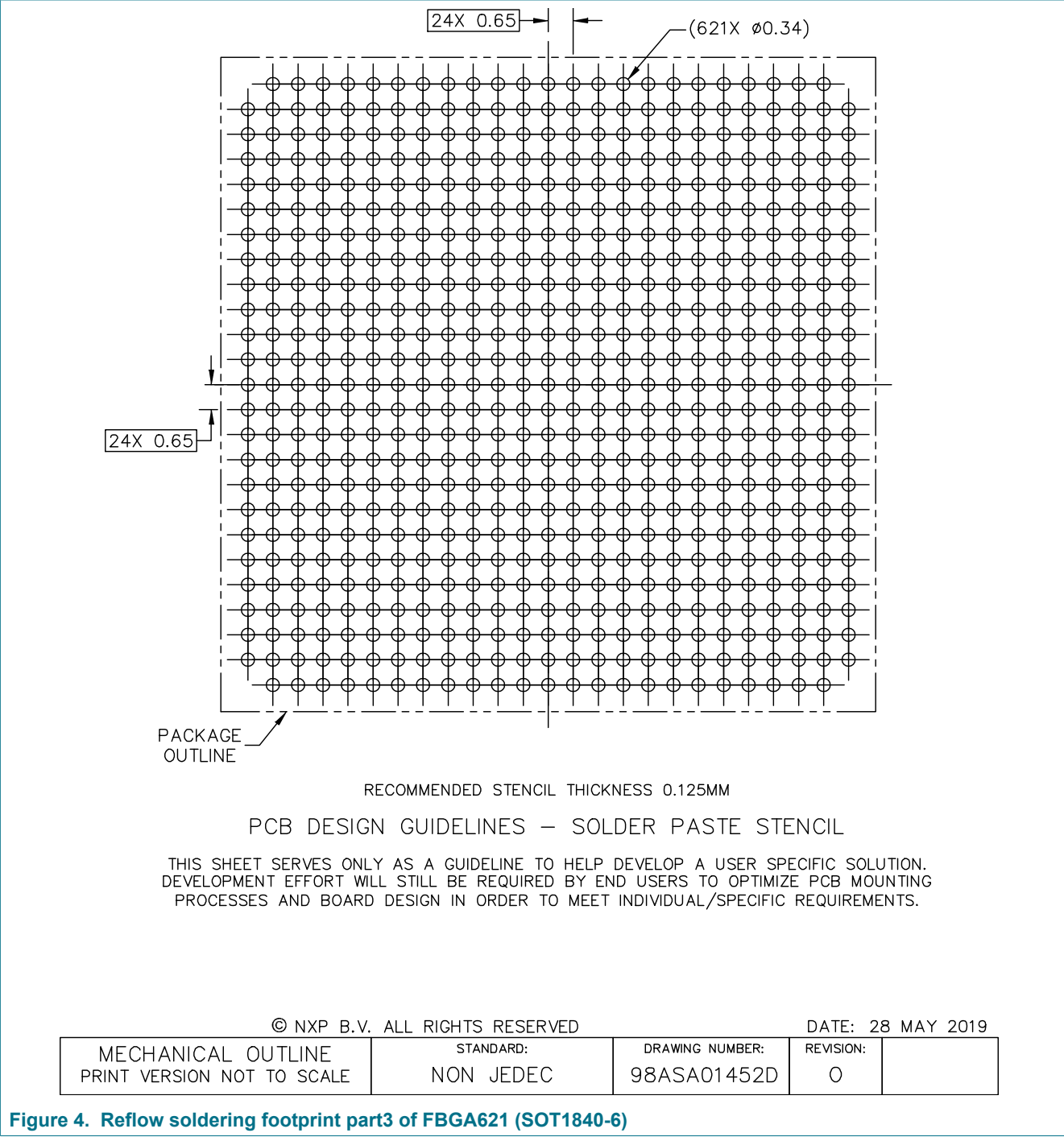


Figure 3. Reflow soldering footprint part2 of FBGA621 (SOT1840-6)

FBGA621, fine-pitch ball grid array package; 621 terminals, 0.65 mm pitch, 17 mm x 17 mm x 1.97 mm body



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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- 7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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DATE: 28 MAY 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01452D	REVISION: 0	
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Figure 5. Package outline note FBGA621 (SOT1840-6)

4 Legal information

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body

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